

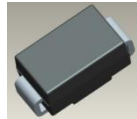
2.0A HIGH VOLTAGE SCHOTTKY BARRIER RECTIFIER

Features

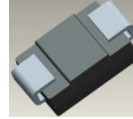
- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Surge Overload Rating to 50A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- High Temperature Soldering: +260°C/10 Second at Terminal
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208③
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.093 grams (Approximate)



Top View



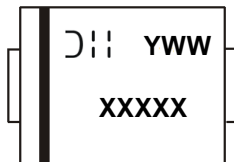
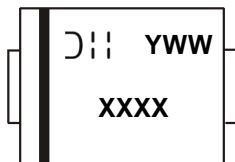
Bottom View

Ordering Information (Note 4)

Part Number	Case	Packaging
B2xx-13-F	SMB	3000/Tape & Reel
B2xxx-13-F	SMB	3000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



XXXX/XXXXX = Product Type Marking Code, ex: B290 (SMB Package)
 DIII = Manufacturers' Code Marking
 YWW = Date Code Marking
 Y = Last Digit of Year (ex: 7 for 2017)
 WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	B270	B280	B290	B2100	Unit
Peak Repetitive Reverse Voltage	V _{RRM}					
Working Peak Reverse Voltage	V _{RWM}	70	80	90	100	V
DC Blocking Voltage	V _R					
RMS Reverse Voltage	V _{R(RMS)}	49	56	63	70	V
Average Rectified Output Current @ T _T = +125°C	I _O	2.0				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	50				A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Terminal (Note 5)	R _{θJT}	15	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V _F	—	—	0.79 0.69	V	I _F = 2.0A, T _A = +25°C I _F = 2.0A, T _A = +100°C
Leakage Current (Note 6)	I _R	—	—	7.0 2.0	μA mA	@ Rated V _R , T _A = +25°C @ Rated V _R , T _A = +100°C
Total Capacitance	C _T	—	—	75	pF	V _R = 4V, f = 1MHz

Notes: 5. Valid provided that terminals are kept at ambient temperature.
6. Short duration pulse test used to minimize self-heating effect.
7. DUT mounted on 1*MRP FR-4 PC board, 2oz.

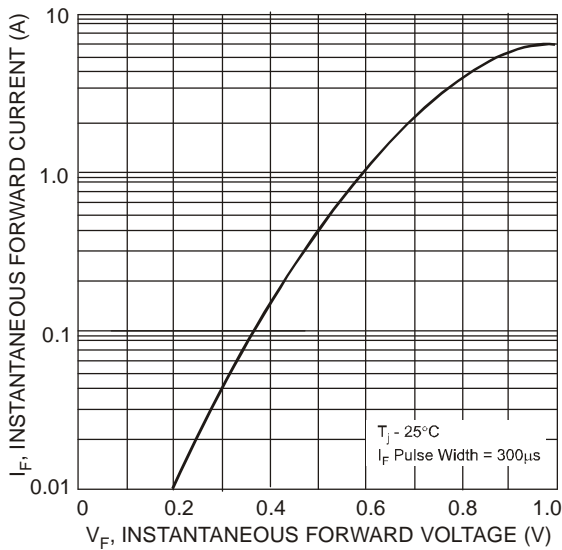


Fig. 1 Typical Forward Characteristics

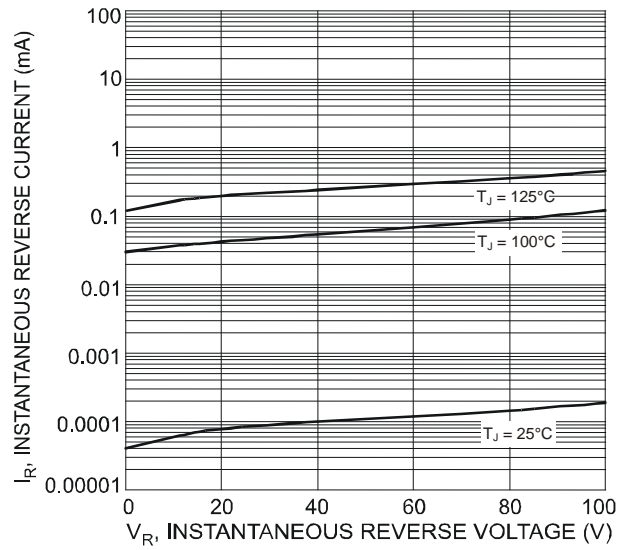


Fig. 2 Typical Reverse Characteristics

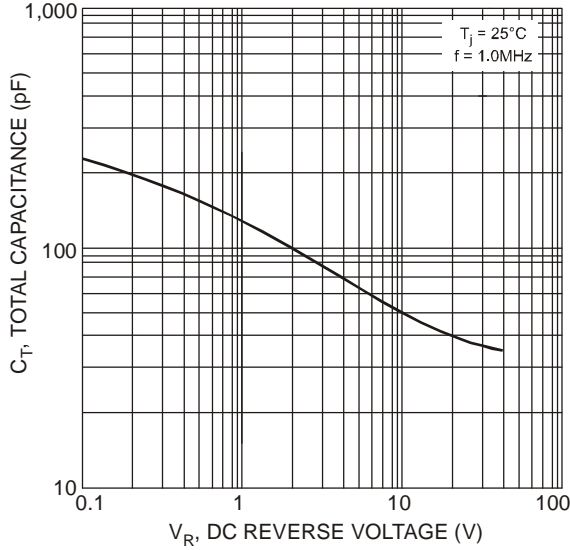


Fig. 3 Total Capacitance vs. Reverse Voltage

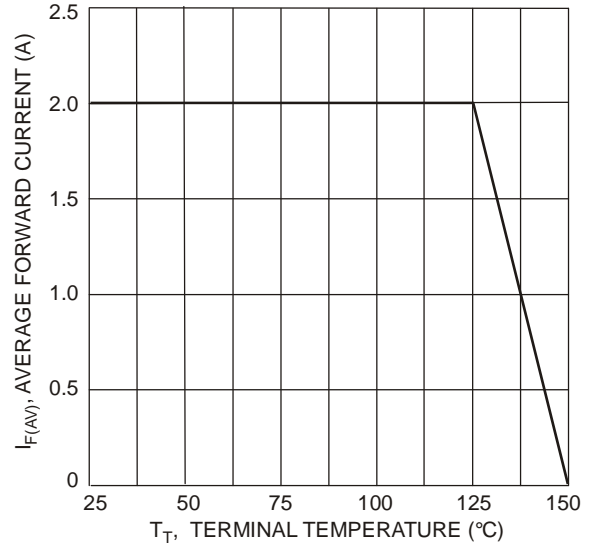


Fig. 4 Forward Current Derating Curve

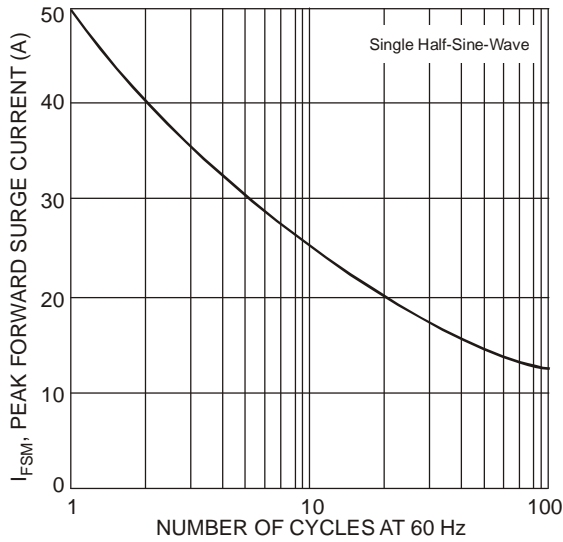


Fig. 5 Max Non-Repetitive Peak Forward Surge Current

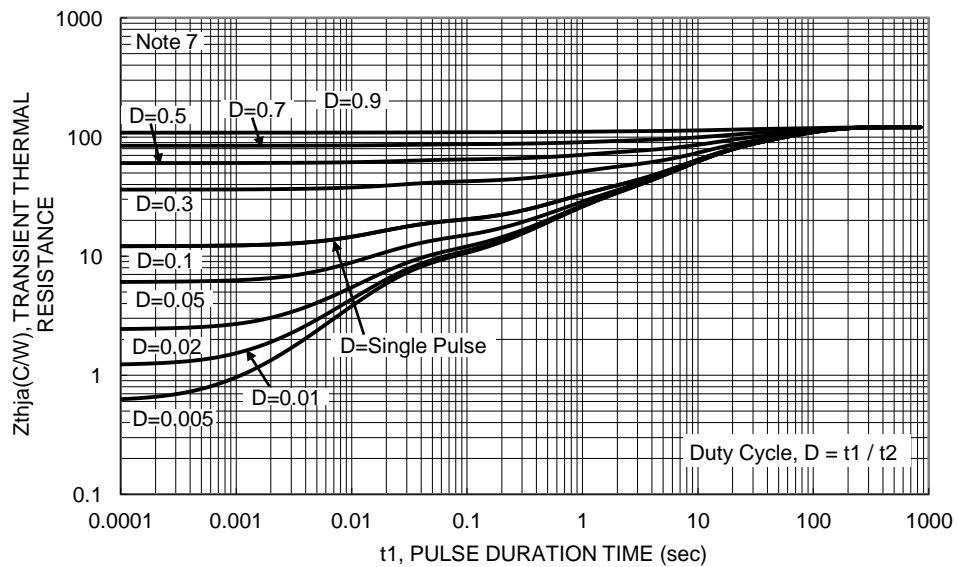


Figure 6. Transient Thermal Resistance

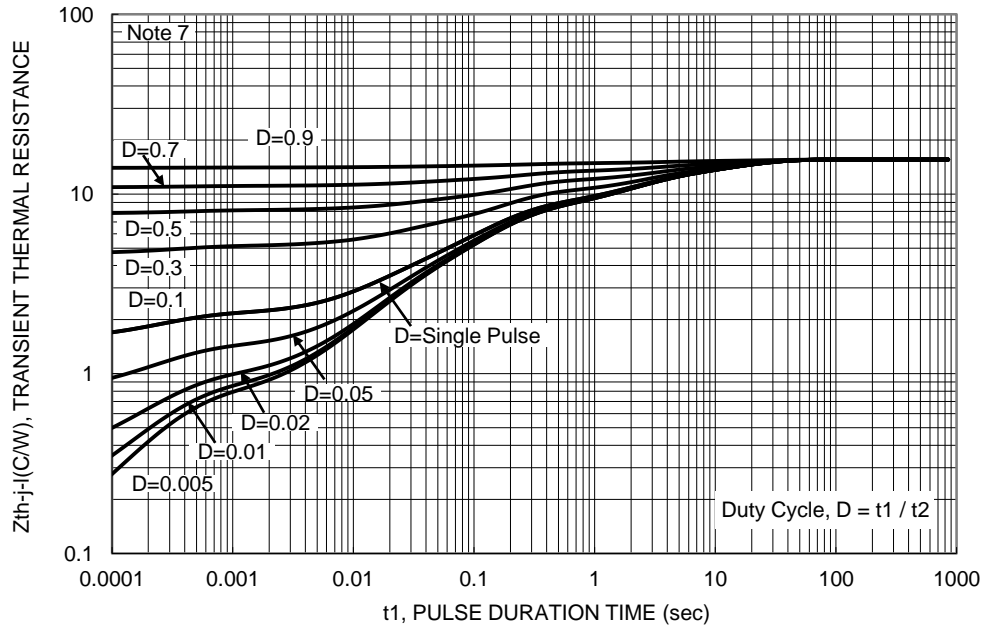
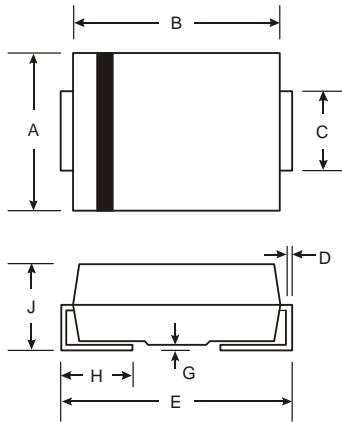


Figure 7. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMB

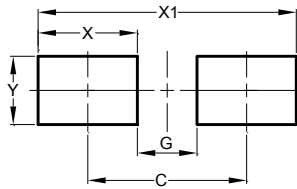


SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMB



Dimensions	Value (in mm)
C	4.30
G	1.80
X	2.50
X1	6.80
Y	2.30

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